**Product / Process Change Notice**

**Parts Affected:**

The CMXTVS5-4 transient voltage suppressor (TVS) in the SOT-26 case.

**Extent of Change:**

The diameter of gold wire used in the assembly process is changing from 1.0 mil to 0.8 mil.

**Reason for Change:**

The new wire size is better suited to the bond pad dimensions of the die.

**Effect of Change:**

This change does not affect the fit, form or function of the devices.

**Qualification:**

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|  **Test** | **Condition** | **Duration** | **Failure rate** |
| **Temperature Cycling (T.C.)** | TA= -55+0℃/-10℃ 15min(Min) TA= +150+15℃/-0℃ 15min(Min) Transfer time less than 1min. The load should reach temp. within 15min  | 1000 Cycles | 0/77  |
| **High Temperature Reverse Bias (HTRB)** | TA=140℃, VR=100%VB DC supply  | 1000 Hours | 0/77  |
| **Resistance to Solder Heat (R.S.H.)** | T =260°C ±5°CDwell time = 10 sec. | 1 Cycle | 0/30  |
| **High Temp. Storage Life (H.T.S.L.)** | TA= +150℃ | 1000 Hours | 0/77 |
| **Thermal Shock Test (T.S.T.)** | TA=0℃ (5 min) ~ +100℃ (5 min)  | 100 Cycles | 0/77 |
| **Temperature Humidity Storage (T.H.S)** | TA=85℃, RH=85%   | 1000 Hours | 0/77 |
| **Autoclave (AC)** | Temperature = 121°C ± 2°C; relative humidity =100%; vapor pressure = 29.7 psia (15psig) | 96 Hours | 0/77 |
| **Solderability (SD)**  | Temperature of solder Pb free: POT=245±5℃ Solder immersion time=5±0.5 sec  | 1 Cycle | 0/10 |

**Effective Date of Change:**

Existing inventory will be shipped until depleted.

**Sample Availability:**

Please contact your salesperson or manufacturer’s representative for samples.

As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor’s Product/Process Change Notification (PCN).

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| Company Name: |  |
| Address: |  |
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| Printed Name: |  |
| Title: |  |
| Signature: |  |
| Date: |  |